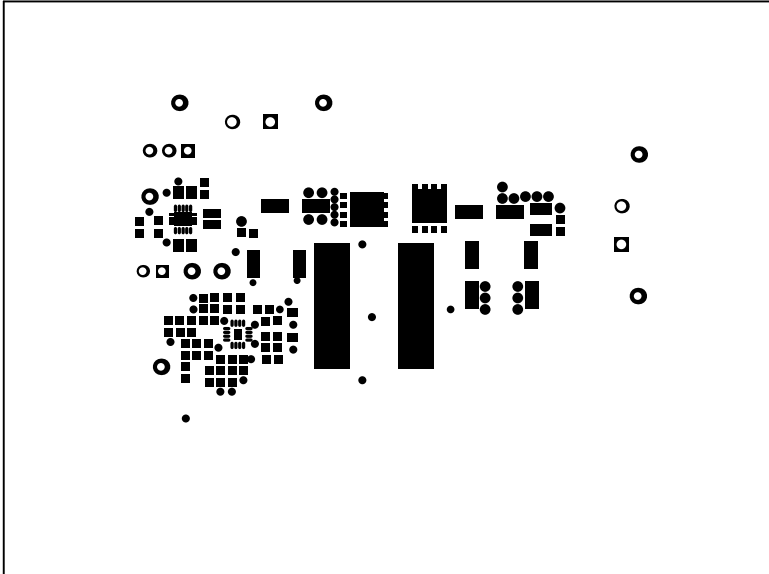
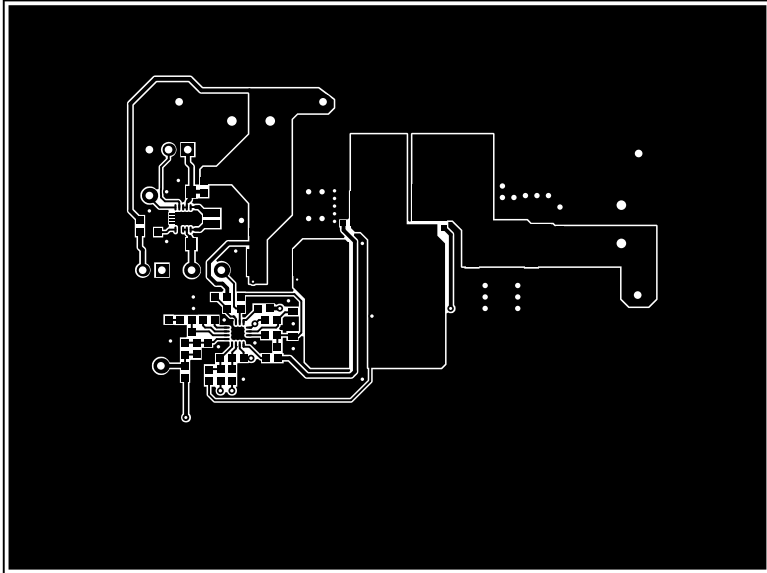


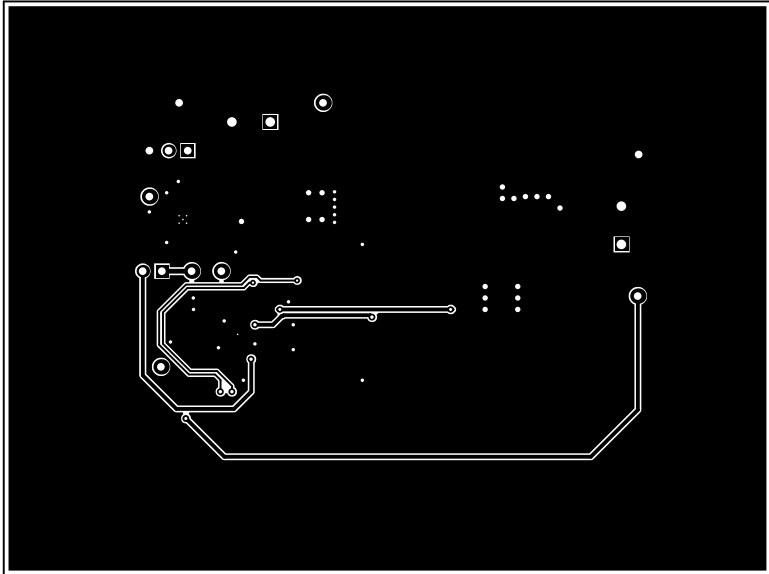
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/20/2013 10:08:39 AM	TEXAS INSTRUMENTS	



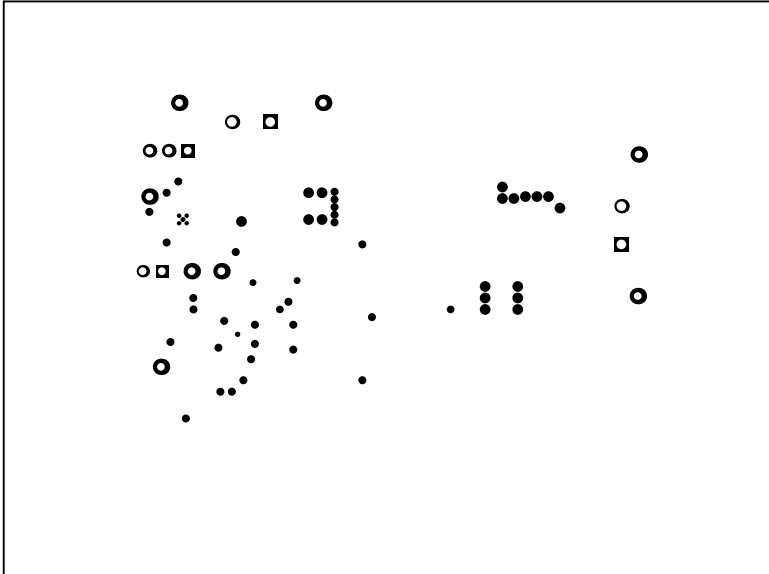
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/20/2013 10:08:39 AM	TEXAS INSTRUMENTS	



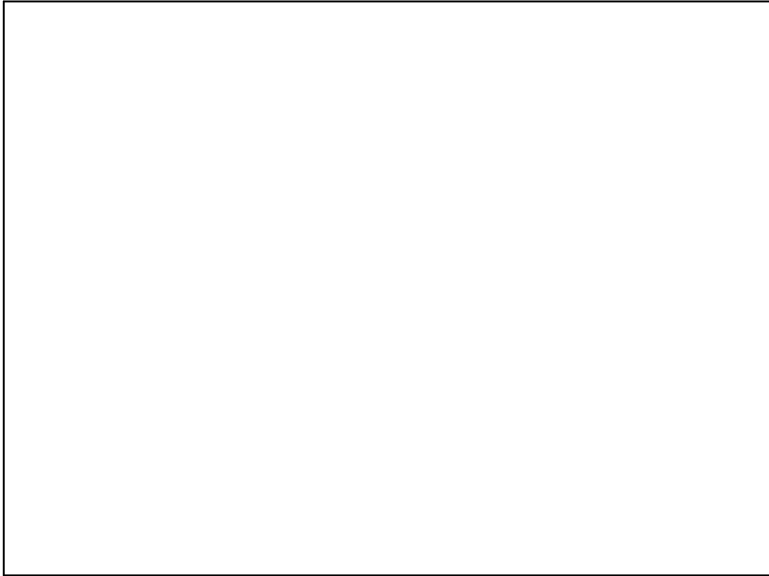
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/20/2013 10:08:40 AM	TEXAS INSTRUMENTS	



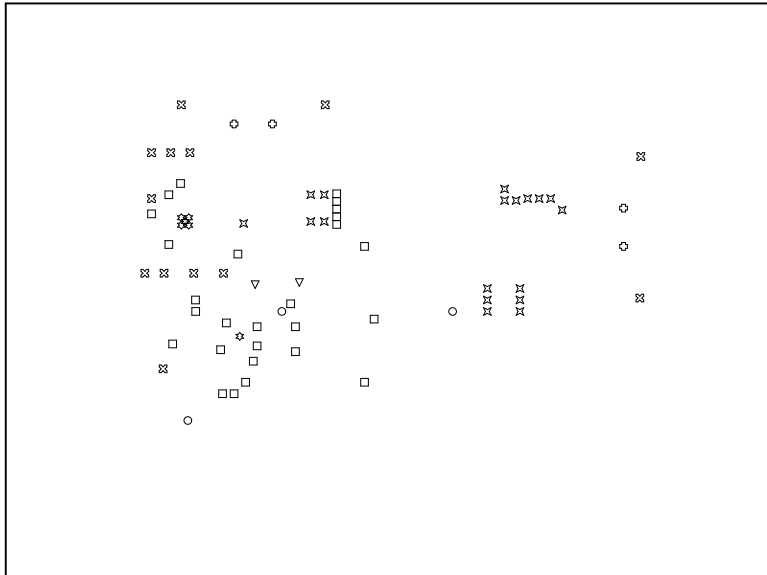
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/20/2013 10:08:40 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/20/2013 10:08:40 AM	TEXAS INSTRUMENTS	



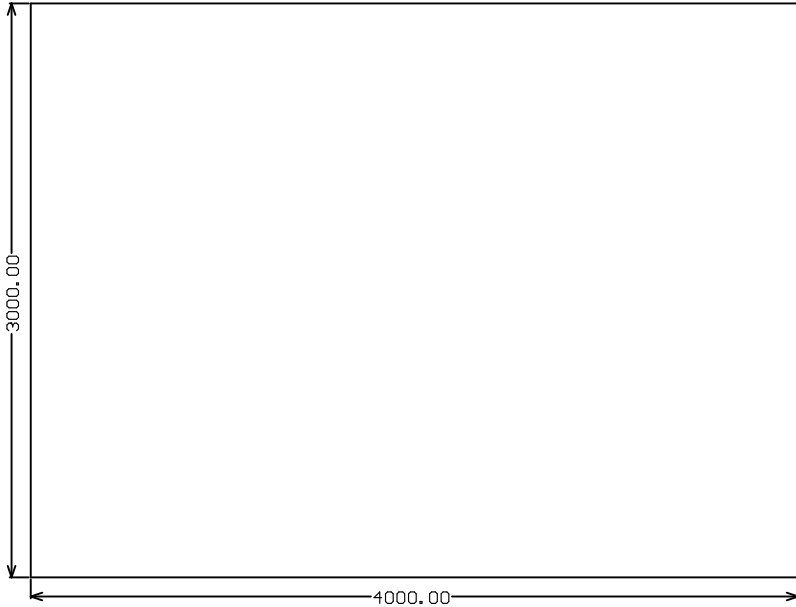
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/20/2013 10:08:41 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
*	6	7.874mil (0.2mm)	PTH	Round
▽	2	12mil (0.305mm)	PTH	Round
○	3	16mil (0.406mm)	PTH	Round
□	27	18mil (0.457mm)	PTH	Round
×	18	28mil (0.711mm)	PTH	Round
⊗	13	40mil (1.016mm)	PTH	Round
⊕	4	49.213mil (1.25mm)	PTH	Round
73 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/20/2013 10:08:41 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/20/2013 10:08:42 AM	TEXAS INSTRUMENTS	

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